

PC3SG21YIZ Series

*Non-zero cross type is also available. (PC3SG11YIZ Series)

V_{DRM}: 600V, Reinforced Insulation Type Zero cross type **Mini-Flat Package** Phototriac Coupler for triggering



Description

PC3SG21YIZ Series reinforced insulation type Phototriac Coupler include an infrared emitting diode (IRED) optically coupled to an output Phototriac.

These devices feature full wave control and are ideal isolated drivers for medium to high current Triacs.

SOP package provides 3.75kV isolation from input to output with superior commutative noise immunity.

Features

- 1. High repetitive peak off-state voltage (V_{DRM} : 600V)
- 2. Zero crossing functionality (Vox : MAX. 35V)
- 3.4 pin Mini-Flat package
- 4. Reinforced insulation type (MIN. 0.4mm internal separation)
- 5. Superior noise immunity (dV/dt : MIN. 1 000V/µs)
- 6. Lead-free components are also available (see Model Line-up section in this datasheet)
- 7. Double transfer mold construction (Ideal for Flow Solderina)
- 8. High isolation voltage between input and output $(V_{iso}(rms) : 3.75kV)$

Agency approvals/Compliance

- 1. Recognized by UL1577 (Double protection isolation), file No. E64380 (as model No. 3SG21)
- 2. Approved by VDE (*)(DIN EN 60747-5-2), file No. 40009162 (as model No. 3SG21)
- 3. Package resin : UL flammability grade (94V-0)
 - (*) DIN EN60747-5-2 : successor standard of DIN VDE0884. Up to Date code "RD" (December 2003), approval of DIN VDF0884 From Date code "S1" (January 2004), approval of DIN EN60747-5-2.

Applications

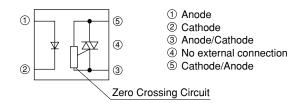
- 1. Triggering for Triacs used to switch on and off devices which require AC Loads. For example heaters, fans, motors, solenoids, and valves.
- 2. AC line control in power supply applications.

Notice The content of data sheet is subject to change without prior notice

In the absence of confirmation by device specification sheets, SHARP takes no responsibility for any defects that may occur in equipment using any SHARP devices shown in catalogs, data books, etc. Contact SHARP in order to obtain the latest device specification sheets before using any SHARP device.

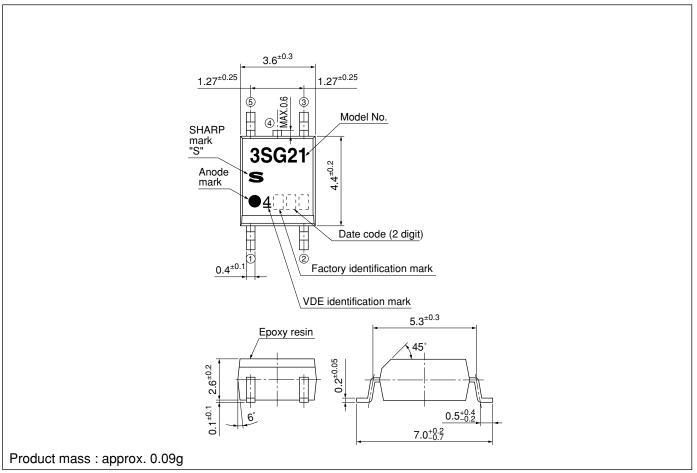


Internal Connection Diagram



Outline Dimensions

(Unit : mm)



*Pin ④ is not allowed external connection



Date code (2 digit)

1st digit			2nd digit		
Year of production			Month of production		
Mark	A.D	Mark	Month	Mark	
A	2002	Р	January	1	
В	2003	R	February	2	
С	2004	S	March	3	
D	2005	Т	April	4	
Е	2006	U	May	5	
F	2007	V	June	6	
Н	2008	W	July	7	
J	2009	Х	August	8	
K	2010	А	September	9	
L	2011	В	October	0	
М	2012	С	November	N	
N	:	:	December	D	
	Year of p Mark A B C D E F H J K L M	Year of production Mark A.D A 2002 B 2003 C 2004 D 2005 E 2006 F 2007 H 2008 J 2009 K 2010 L 2011 M 2012	Year of production Mark A.D Mark A 2002 P B 2003 R C 2004 S D 2005 T E 2006 U F 2007 V H 2008 W J 2009 X K 2010 A L 2011 B M 2012 C	Year of productionMonth ofMarkA.DMarkMonthA2002PJanuaryB2003RFebruaryC2004SMarchD2005TAprilE2006UMayF2007VJuneH2008WJulyJ2009XAugustK2010ASeptemberL2011BOctoberM2012CNovember	

repeats in a 20 year cycle

Factory identification mark

Factory identification Mark	Country of origin	
no mark	Japan	
	Indonesia	
$\overline{\nabla}$	Philippines	
	China	

* This factory marking is for identification purpose only.

Please contact the local SHARP sales representative to see the actural status of the production.

Rank mark

There is no rank mark indicator and currently there are no ranks offered for this device.

0.2mm or more

L

Soldering area

Absolute Maximum Ratings

■ Absolute Maximum Ratings (T _a =25°				
	Parameter	Symbol	Rating	Unit
Innut	Forward current	I _F	50	mA
Input	Reverse voltage	V _R	6	V
	RMS ON-state current	I _T (rms)	0.05	Α
Output	Peak one cycle surge current	I _{surge}	0.6 *3	А
	Repetitive peak OFF-state voltage	V _{DRM}	600	V
^{*1} Isolation voltage		V _{iso} (rms)	3.75	kV
Operating temperature		T _{opr}	-30 to +100	°C
Storage temperature		T _{stg}	-40 to +125	°C
* ² Soldering temperature		T _{sol}	260	°C

*1 40 to 60%RH, AC for 1minute, f=60Hz *2 For 10s *3 f=50Hz sine wave

Electro-optical Characteristics

Electro	o-optical Characteristics					($(T_a=25^{\circ}C)$
	Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Input	Forward voltage	V _F	I _F =20mA	-	1.2	1.4	V
mput	Reverse current	IR	V _R =3V	_	_	10	μΑ
	Repetitive peak OFF-state current	I _{DRM}	$V_D = V_{DRM}$	-	-	1	μΑ
	ON-state voltage	VT	I _T =0.05A	_	_	2.5	V
Output	Holding current	I _H	V _D =6V	0.1	_	3.5	mA
-	Critical rate of rise of OFF-state voltage	dV/dt	$V_{D}=1/\sqrt{2} \cdot V_{DRM}$	1 000	-	-	V/µs
	Zero-cross voltage	V _{OX}	I _F =15mA, Resistance load	-	-	35	V
Transfer	Minimum trigger current	I _{FT}	$V_{D}=6V, R_{L}=100\Omega$	-	-	10	mA
charac-	Isolation resistance	R _{ISO}	DC500V, 40 to 60%RH	5×10 ¹⁰	1011	-	Ω
teristics	Turn-on time	t _{on}	$V_D=6V, R_L=100\Omega, I_F=20mA$	-	_	50	μs

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■ Model Line-up (1) (Lead-free components)

Shipping Package	Sle	eve	$I_{FT}[mA]$
Shipping I ackage	100pcs	sleeve	
DIN EN60747-5-2		Approved	$(V_D=6V, R_L=100\Omega)$
Model No.		PC3SG21YIZ0F	MAX.10

■ Model Line-up (2) (Lead solder plating components)

Shipping Package	Sle	eve	
100pcs/sleeve		/sleeve	$I_{FT}[mA]$
DIN EN60747-5-2		Approved	$(V_D=6V, R_L=100\Omega)$
Model No.		PC3SG21YIZ	MAX.10

Please contact a local SHARP sales representative to inquire about production status.



Fig.1 Forward Current vs. Ambient Temperature

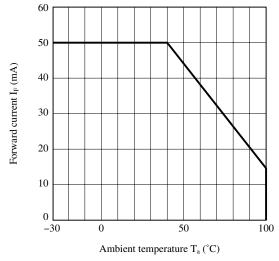
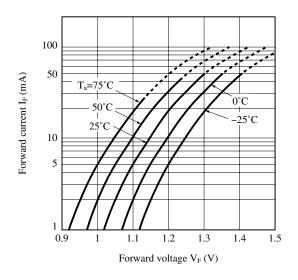


Fig.3 Forward Current vs. Forward Voltage





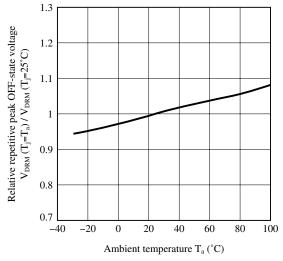


Fig.2 RMS ON-state Current vs. Ambient Temperature

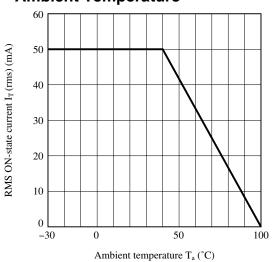


Fig.4 Minimum Trigger Current vs. Ambient Temperature

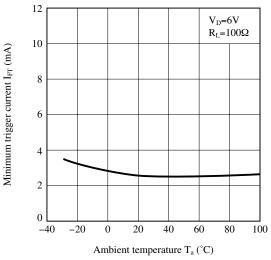


Fig.6 ON-state Voltage vs. Ambient Temperature

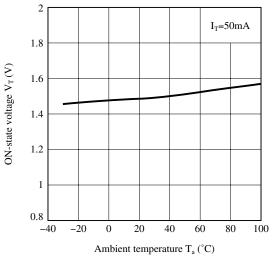
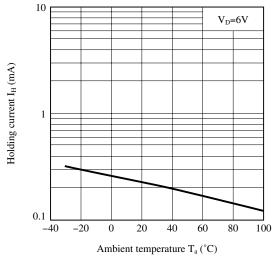
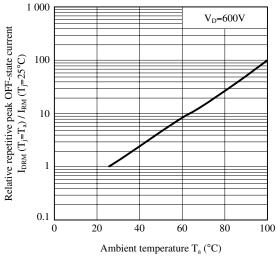




Fig.7 Holding Current vs. Ambient Temperature









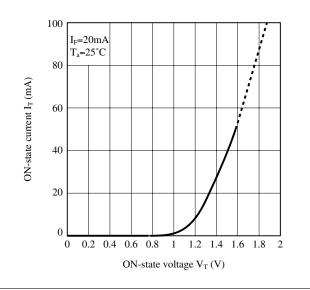


Fig.8 Repetitive Peak OFF-state Current vs. OFF-state Voltage

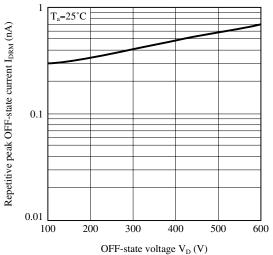
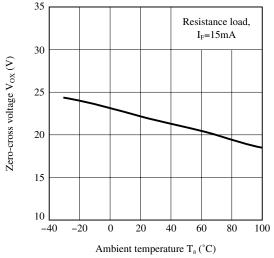


Fig.10 Zero-cross Voltage vs. Ambient Temperature



Remarks : Please be aware that all data in the graph are just for reference.



Design Considerations

Design guide

In order for the Phototriac to turn off, the triggering current (I_F) must be 0.1mA or less.

Please refrain from using these devices in a direct drive configuration. These Phototriac Coupler are intended to be used as triggering device for main Triacs. Please ensure that the output rating of these devices will be sufficient for triggering the main output Triac of your choice. Failure to do may result in malfunctions.

For applications with inductive loads such as motors, please use caution in utilizing a zero crossing type Phototraiac Coupler as this may cause undesired operations due to the phase difference between voltage and current of load.

For designs that will experience excessive noise or sudden changes in load voltage, please include an appropriate snubber circuit as shown in the below circuit. Please keep in mind the Sharp Phototriac Coupler incorporate superrior dV/dt ratings which can eliminate the need for a snubber circuit.

For over voltage protection, a Varistor may be used.

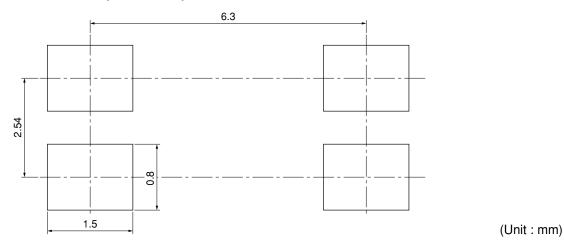
Degradation

In general, the emission of the IRED used in Phototriac Couplers will degrade over time.

In the case where long term operation and / or constant extreme temperature fluctuations will be applied to the devices, please allow for a worst case scenario of 50% degradation over 5years.

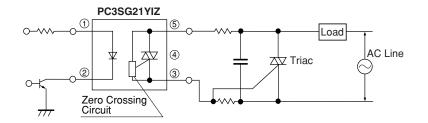
Therefore in order to maintain proper operation, a design implementing these Phototriac Couplers should provide at least twice the minimum required triggering current from initial operation.

• Recommended Foot Print (reference)





• Standard Circuit (Medium/High Power Triac Drive Circuit)



Note) Please add the snubber circuit according to a condition. Any snubber or varistor used for the above mentioned scenarios should be located as close to the main output triac as possible.

☆ For additional design assistance, please review our corresponding Optoelectronic Application Notes.

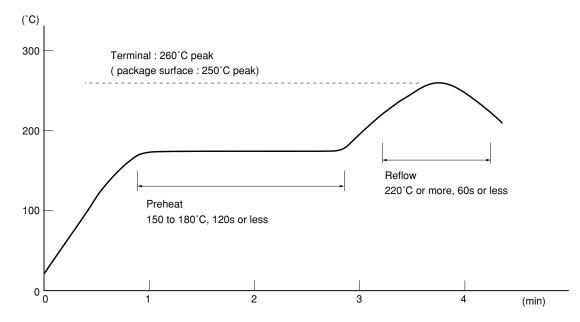


Manufacturing Guidelines

Soldering Method

Reflow Soldering:

Reflow soldering should follow the temperature profile shown below. Soldering should not exceed the curve of temperature profile and time. Please don't solder more than twice.



Flow Soldering :

Due to SHARP's double transfer mold construction submersion in flow solder bath is allowed under the below listed guidelines.

Flow soldering should be completed below 260°C and within 10s. Preheating is within the bounds of 100 to 150°C and 30 to 80s. Please don't solder more than twice.

Hand soldering

Hand soldering should be completed within 3s when the point of solder iron is below 400°C. Please don't solder more than twice.

Other notices

Please test the soldering method in actual condition and make sure the soldering works fine, since the impact on the junction between the device and PCB varies depending on the tooling and soldering conditions.



• Cleaning instructions

Solvent cleaning :

Solvent temperature should be 45°C or below. Immersion time should be 3minutes or less.

Ultrasonic cleaning :

The impact on the device varies depending on the size of the cleaning bath, ultrasonic output, cleaning time, size of PCB and mounting method of the device.

Therefore, please make sure the device withstands the ultrasonic cleaning in actual conditions in advance of mass production.

Recommended solvent materials :

Ethyl alcohol, Methyl alcohol and Isopropyl alcohol.

In case the other type of solvent materials are intended to be used, please make sure they work fine in actual using conditions since some materials may erode the packaging resin.

Presence of ODC

This product shall not contain the following materials.

And they are not used in the production process for this device.

Regulation substances : CFCs, Halon, Carbon tetrachloride, 1.1.1-Trichloroethane (Methylchloroform) Specific brominated flame retardants such as the PBBOs and PBBs are not used in this product at all.



■ Package specification

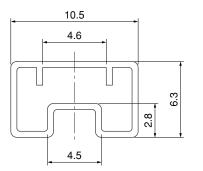
Sleeve package

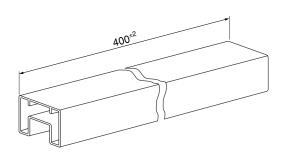
Package materials Sleeve : HIPS (with anti-static material) Stopper : Styrene-Elastomer

Package method

MAX. 100pcs of products shall be packaged in a sleeve.Both ends shall be closed by tabbed and tabless stoppers.The product shall be arranged in the sleeve with its anode mark on the tabless stopper side.MAX. 50 sleeves in one case.

Sleeve outline dimensions





(Unit : mm)

SHARP

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(i) The devices in this publication are designed for use in general electronic equipment designs such as:

- --- Personal computers
- --- Office automation equipment
- --- Telecommunication equipment [terminal]
- --- Test and measurement equipment
- --- Industrial control
- --- Audio visual equipment
- --- Consumer electronics

(ii) Measures such as fail-safe function and redundant design should be taken to ensure reliability and safety when SHARP devices are used for or in connection with equipment that requires higher reliability such as:

- --- Transportation control and safety equipment (i.e., aircraft, trains, automobiles, etc.)
- --- Traffic signals
- --- Gas leakage sensor breakers
- --- Alarm equipment
- --- Various safety devices, etc.

(iii) SHARP devices shall not be used for or in connection with equipment that requires an extremely high level of reliability and safety such as:

- --- Space applications
- --- Telecommunication equipment [trunk lines]
- --- Nuclear power control equipment
- --- Medical and other life support equipment (e.g., scuba).

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